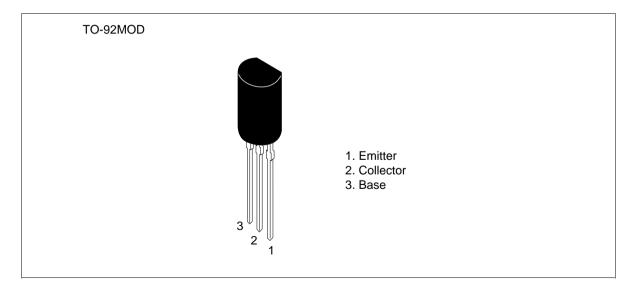
Silicon PNP Epitaxial

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Application

- Low frequency power amplifier
- Complementary pair with 2SD787 and 2SD788

Outline





Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

Item	Symbol	2SB738	2SB739	Unit
Collector to base voltage	V _{CBO}	-20	-20	V
Collector to emitter voltage	V _{CEO}	-16	-20	V
Emitter to base voltage	V _{EBO}	-6	-6	V
Collector current	I _c	-2	-2	А
Collector power dissipation	Pc	0.9	0.9	W
Junction temperature	Tj	150	150	°C
Storage temperature	Tstg	-55 to +150	-55 to +150	°C

Electrical Characteristics (Ta = 25°C)

		2SB738		2SB739					
ltem	Symbol	Min	Тур	Max	Min	Тур	Мах	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	-20	_	_	-20	_	_	V	$I_{c} = -10 \ \mu A, I_{E} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	-16	—	—	-20	—	—	V	$I_c = -1 \text{ mA}, \text{ R}_{BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	-6	—	—	-6	—	—	V	$I_{\rm E} = -10 \ \mu A, \ I_{\rm C} = 0$
Collector cutoff current	I _{CBO}	—	_	-2	_	_	-2	μA	$V_{\rm CB} = -16 \text{ V}, \ I_{\rm E} = 0$
Emitter cutoff current	I _{EBO}	—	_	-0.2	—	—	-0.2	μA	$V_{EB} = -6 V, I_{C} = 0$
DC current transfer ratio	h_{FE}^{*1}	100	_	320	100	—	320		$V_{ce} = -2 V, I_c = -0.1 A$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	—	—	-0.3	—	_	-0.3	V	$I_{\rm c} = -1$ A, $I_{\rm B} = -0.1$ A
Gain bandwidth product	f _T	—	150	—	—	150		MHz	$V_{ce} = -2 \text{ V}, \text{ I}_{c} = -10 \text{ mA}$
Collector output capacitance	e Cob		50	—		50		pF	$V_{CB} = -10 \text{ V}, I_E = 0,$ f = 1 MHz

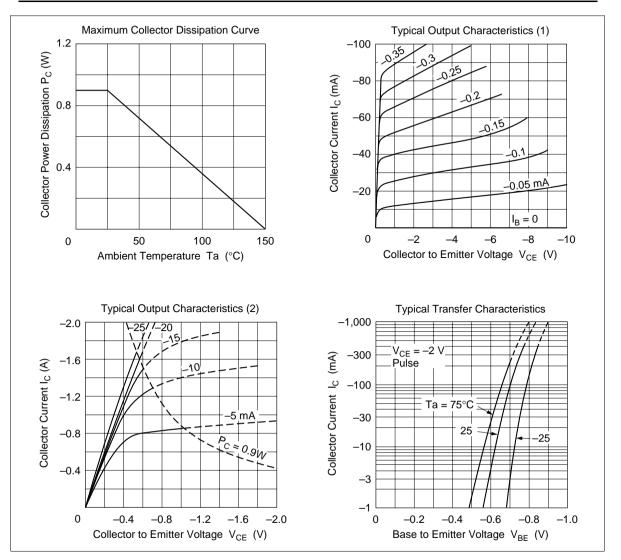
Note: 1. The 2SB738 and 2SB739 are grouped by $h_{\mbox{\tiny FE}}$ as follows.

В

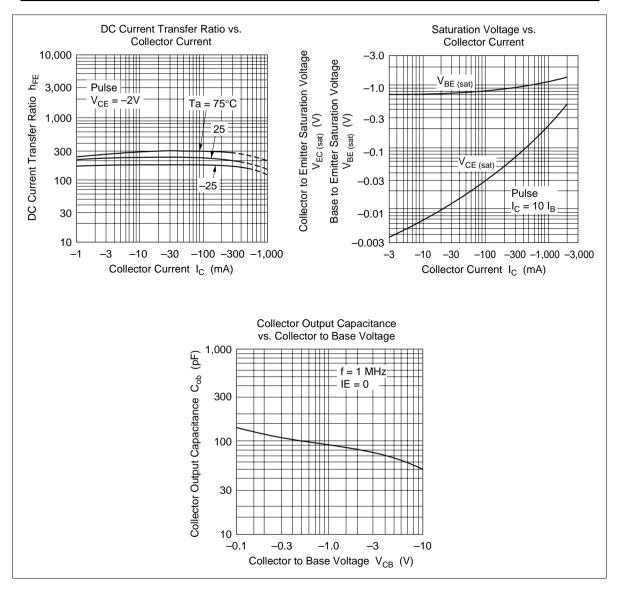
100 to 200 160 to 320

С

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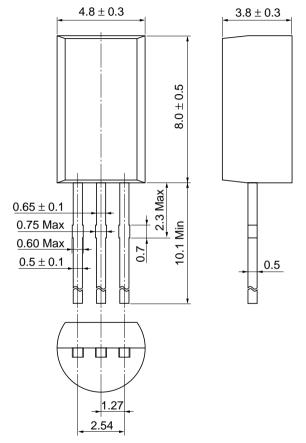


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Unit: mm



Hitachi Code	TO-92 Mod
JEDEC	_
EIAJ	Conforms
Weight (reference value)	0.35 g

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